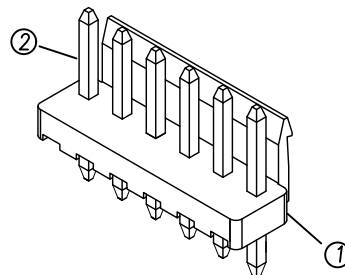
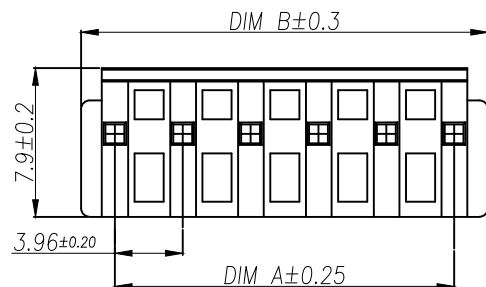
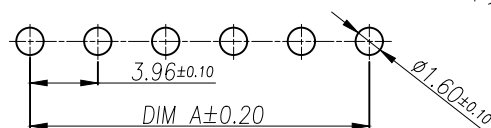
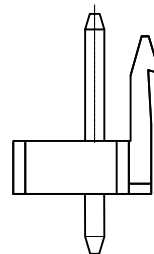
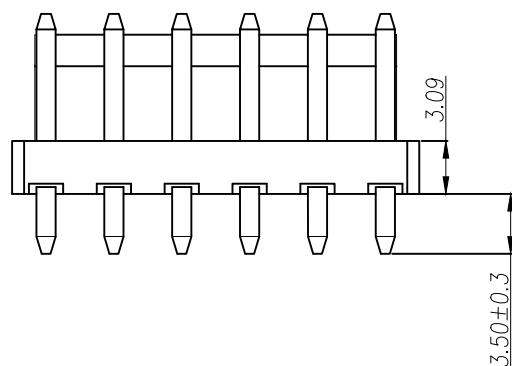


PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE

- 技术要求:
- 1、塑件材料:PA66 (UL-94V-0)
 - 2、接触件:黄铜镀锡
 - 3、接触电阻: $\leq 20\text{m}\Omega$
 - 4、绝缘电阻: $\geq 1000\text{M}\Omega$
 - 5、额定电压:250V AC DC
 - 6、额定电流:3.0A AC DC
 - 7、耐压:能承受1000V AC/Min ute
 - 8、工作温度: $-25^{\circ}\sim +85^{\circ}$
 - 9、可焊性试验:浸锡面积 $\geq 95\%$ 温度 $235^{\circ}\pm 5^{\circ}$,时间 2.5 ± 0.5 秒
 - 10、铅和镉等六大有害物质含量要符合环保要求

Part No	PIN	A	B
XY-VH-2A	2	3.96	7.92
XY-VH-3A	3	7.92	11.88
XY-VH-4A	4	11.88	15.84
XY-VH-5A	5	15.84	19.80
XY-VH-6A	6	19.80	23.76
XY-VH-7A	7	23.76	27.72
XY-VH-8A	8	27.72	31.68
XY-VH-9A	9	31.68	35.64
XY-VH-10A	10	35.64	39.60
XY-VH-11A	11	39.60	43.56
XY-VH-12A	12	43.56	47.52
XY-VH-13A	13	47.52	51.48
...	...	...	...
XY-VH-20A	20	(20-1)*3.96	20*3.96

SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN,再 镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	白色
序号	名称	材料	数量	附注
DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyconn Electronics Co.,Ltd		
.X ± 0.35	X.* $\pm 5^{\circ}$	APR. Alex	TITLE: WAFER 3.96mm H3.0mm 180° DIP	
.XX ± 0.25	.X.* $\pm 3^{\circ}$	CHK. Jack	DWG NO. XY-VH-NA	
.XXX ± 0.15	.XX.* $\pm 1^{\circ}$	DRA. Can	PROJ.	CUSTOMER DRAWING
SIZE A4	SCALE 1:1	SHEET 1/1	REV. A	